

Lead Free Qualification Status by Package Type



Updated: October 1st, 2004

Package	Lead Count	Body Size	Estimated Qualification Date	Estimated Production Date	Status October 2004
LQFP	44, 64	10x10x1.4 mm	July-03	August-03	Qualified
LQFP	100	14x14x1.4 mm	December-03	January-04	Qualified
LQFP	128	14x20x1.4 mm	TBD	TBD	Not Started
LQFP	144	20x20x1.4 mm	September-03	October-03	Qualified
LQFP	208	28x28x1.4 mm	November-04	December-04	Reliability Testing
LQFP	48	7x7x1.4 mm	June-03	July-03	Qualified
MQFP	100,128	14x20x2.7 mm	TBD	TBD	Not Started
MQFP	208,256	28x28x3.3 mm	November-04	December-04	Qual Lot Start
MQFP	240	32x32x3.4 mm	New Product Qualification	New Product Qualification	New Product Qualification
QFN	20, 28, 32	5x5 mm	New Product Qualification	New Product Qualification	New Product Qualification
PBGA	256, 272	27x27 mm	May-03	June-03	Qualified
PBGA	352	27x27 mm	TBD	TBD	Not Started
PBGA	256	17x17 mm	TBD	TBD	Not Started
PDIP	8, 14, 16, 24	300 mil	Not Planned	Not Planned	Not Planned

Lead Free Qualification Status by Package Type



Updated: October 1st, 2004

Package	Lead Count	Body Size	Estimated Qualification Date	Estimated Production Date	Status October 2004
PDIP	28, 40	600 mil	Not Planned	Not Planned	Not Planned
PLCC	44	653x653 mil	July-03	August-03	Qualified
PLCC	28	453x453 mils	October-04	November-04	Reliability Testing
SOIC	8	150 mil	January-03	February-03	Qualified
SOIC	16	150 mil	January-04	February-04	Qualified
SOIC	8	209 mil	July-04	August-04	Qualified
SOIC	24, 28	300 mil	March-04	April-04	Qualified
SOIC	16,20	300 mil	October-04	November-04	Reliability Testing
SSOP	16,20,24,28	5.3 mm	January-03	February-03	Qualified
TFBGA	204	13x13 mm	TBD	TBD	Not Started
TSSOP	10	3.0 mm	New Product Qualification	New Product Qualification	New Product Qualification
TSSOP	16,20,24,28	4.4 mm	January-03	February-03	Qualified

Key:

	Qualified
	In-Process
	Not Started